LNJ208R8ARA

Surface Mounting Chip LED

SS Type

■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter | Symbol | Rating | Unit | |
|-------------------------------|------------------|-------------|------|--|
| Power dissipation | P_{D} | 50 | mW | |
| Forward current | I_{F} | 20 | mA | |
| Pulse forward current * | I_{FP} | 100 | mA | |
| Reverse voltage | V _R | 3 | V | |
| Operating ambient temperature | T _{opr} | -25 to +85 | °C | |
| Storage temperature | T _{stg} | -40 to +100 | °C | |

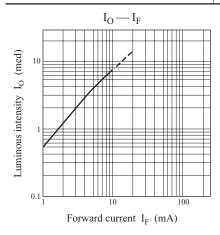
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

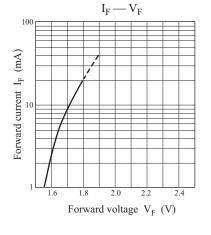
■ Lighting Color

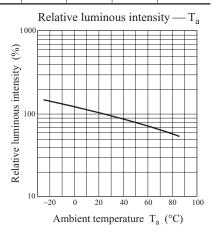
• Red

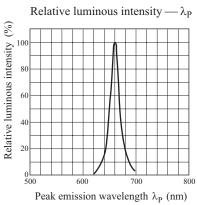
■ Electro-Optical Characteristics $T_a = 25$ °C

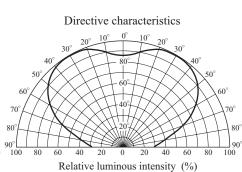
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|--------------------------|------------------|-----------------------|------|------|-----|------|
| Luminous intensity | I _O | $I_F = 10 \text{ mA}$ | 2.75 | 6.7 | | mcd |
| Reverse current | I _R | $V_R = 3 V$ | | | 100 | μА |
| Forward voltage | V _F | $I_F = 10 \text{ mA}$ | | 1.72 | 2.5 | V |
| Peak emission wavelength | $\lambda_{ m P}$ | $I_F = 10 \text{ mA}$ | | 660 | | nm |
| Spectral half band width | Δλ | $I_F = 10 \text{ mA}$ | | 20 | | nm |

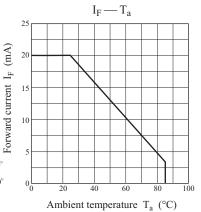








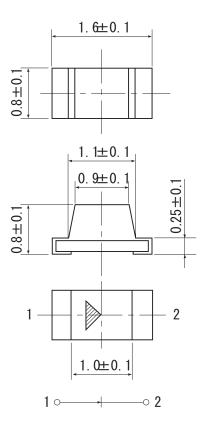




LNJ208R8ARA Panasonic

■ Package (Unit: mm)

KLTFTN2K0800



- Pin name
 - 1: Anode
 - 2: Cathode

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